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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	1024
Total RAM Bits	8192
Number of I/O	193
Number of Gates	30000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C
Package / Case	240-BFQFP
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at40k20al-1eqc

Email: info@E-XFL.COM

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Cache Logic Design The AT40KAL, AT6000 and FPSLIC families are capable of implementing Cache Logic (dynamic full/partial logic reconfiguration, without loss of data, on-the-fly) for building adaptive logic and systems. As new logic functions are required, they can be loaded into the logic cache without losing the data already there or disrupting the operation of the rest of the chip; replacing or complementing the active logic. The AT40KAL can act as a reconfigurable coprocessor.

Automatic Component Generators The AT40KAL FPGA family is capable of implementing user-defined, automatically generated, macros in multiple designs; speed and functionality are unaffected by the macro orientation or density of the target device. This enables the fastest, most predictable and efficient FPGA design approach and minimizes design risk by reusing already proven functions. The Automatic Component Generators work seamlessly with industry standard schematic and synthesis tools to create the fastest, most efficient designs available.

The patented AT40KAL series architecture employs a symmetrical grid of small yet powerful cells connected to a flexible busing network. Independently controlled clocks and resets govern every column of cells. The array is surrounded by programmable I/O.

Devices range in size from 5,000 to 50,000 usable gates in the family, and have 256 to 3,048 registers. Pin locations are consistent throughout the AT40KAL series for easy design migration in the same package footprint. The AT40KAL series FPGAs utilize a reliable 0.35µ triple-metal, CMOS process and are 100% factory-tested. Atmel's PC-and workstation-based integrated development system (IDS) is used to create AT40KAL series designs. Multiple design entry methods are supported.

The Atmel architecture was developed to provide the highest levels of performance, functional density and design flexibility in an FPGA. The cells in the Atmel array are small, efficient and can implement any pair of Boolean functions of (the same) three inputs or any single Boolean function of four inputs. The cell's small size leads to arrays with large numbers of cells, greatly multiplying the functionality in each cell. A simple, high-speed busing network provides fast, efficient communication over medium and long distances.











Cell Connections

Figure 4(a) depicts direct connections between a cell and its eight nearest neighbors. Figure 4(b) shows the connections between a cell and five horizontal local buses (1 per busing plane) and five vertical local buses (1 per busing plane).





(a) Cell-to-cell Connections

(b) Cell-to-bus Connections

The Cell

Figure 5 depicts the AT40KAL cell. Configuration bits for separate muxes and pass gates are independent. All permutations of programmable muxes and pass gates are legal. $V_n (V_1 - V_5)$ is connected to the vertical local bus in plane n. $H_n (H_1 - H_5)$ is connected to the horizontal local bus in plane *n*. A local/local turn in plane n is achieved by turning on the two pass gates connected to V_n and H_n . Pass gates are opened to let signals into the cell from a local bus or to drive a signal out onto a local bus. Signals coming into the logic cell on one local bus plane can be switched onto another plane by opening two of the pass gates. This allows bus signals to switch planes to achieve greater route ability. Up to five simultaneous local/local turns are possible.

The AT40KAL FPGA core cell is a highly configurable logic block based around two 3input LUTs (8 x 1 ROM), which can be combined to produce one 4-input LUT. This means that any core cell can implement two functions of 3 inputs or one function of 4 inputs. There is a Set/Reset D flip-flop in every cell, the output of which may be tri-stated and fed back internally within the core cell. There is also a 2-to-1 multiplexer in every cell, and an upstream AND gate in the "front end" of the cell. This AND gate is an important feature in the implementation of efficient array multipliers.

With this functionality in each core cell, the core cell can be configured in several "modes". The core cell flexibility makes the AT40KAL architecture well suited to most digital design application areas, see Figure 6.

Figure 5. The Cell



- X = Diagonal Direct Connect or Bus
- Y = Orthogonal Direct Connect or Bus
- W = Bus Connection
- Z = Bus Connection
- FB = Internal Feedback





Reading and writing of the 10 ns 32 x 4 dual-port FreeRAM are independent of each other. Reading the 32 x 4 dual-port RAM is completely asynchronous. Latches are transparent; when Load is logic 1, data flows through; when Load is logic 0, data is latched. These latches are used to synchronize Write Address, Write Enable Not, and Din signals for a synchronous RAM. Each bit in the 32 x 4 dual-port RAM is also a transparent latch. The front-end latch and the memory latch together form an edge-triggered flip flop. When a nibble (bit = 7) is (Write) addressed and LOAD is logic 1 and WE is logic 0, data flows through the bit. When a nibble is not (Write) addressed or LOAD is logic 0 or WE is logic 1, data is latched in the nibble. The two CLOCK muxes are controlled together; they both select CLOCK (for a synchronous RAM) or they both select "1" (for an asynchronous RAM). CLOCK is obtained from the clock for the sector-column immediately to the left and immediately above the RAM block. Writing any value to the RAM clear byte during configuration clears the RAM (see the "AT40K/40KAL Configuration Series" application note at www.atmel.com).





Figure 9 on page 13 shows an example of a RAM macro constructed using the AT40KAL's FreeRAM cells. The macro shown is a 128 x 8 dual-ported asynchronous RAM. Note the very small amount of external logic required to complete the address decoding for the macro. Most of the logic cells (core cells) in the sectors occupied by the RAM will be unused: they can be used for other logic in the design. This logic can be automatically generated using the macro generators.



Figure 10. Clocking (for One Column of Cells)



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	8

I/O Structure	The AT40KAL has registered I/Os and group enable every sector for tri-states on obuf's.
PAD	The I/O pad is the one that connects the I/O to the outside world. Note that not all I/Os have pads: the ones without pads are called Unbonded I/Os. The number of unbonded I/Os varies with the device size and package. These unbonded I/Os are used to perform a variety of bus turns at the edge of the array.
PULL-UP/PULL-DOWN	Each pad has a programmable pull-up and pull-down attached to it. This supplies a weak "1" or "0" level to the pad pin. When all other drivers are off, this control will dictate the signal level of the pad pin.
	The input stage of each I/O cell has a number of parameters that can be programmed either as properties in schematic entry or in the I/O Pad Attributes editor in IDS.
CMOS	The threshold level is a CMOS-compatible level.
SCHMITT	A Schmitt trigger circuit can be enabled on the inputs. The Schmitt trigger is a regenera- tive comparator circuit that adds 1V hysteresis to the input. This effectively improves the rise and fall times (leading and trailing edges) of the incoming signal and can be useful for filtering out noise.
DELAYS	The input buffer can be programmed to include four different intrinsic delays as specified in the AC timing characteristics. This feature is useful for meeting data hold require- ments for the input signal.
DRIVE	The output drive capabilities of each I/O are programmable. They can be set to FAST, MEDIUM or SLOW (using IDS tool). The FAST setting has the highest drive capability (20 mA at 5V) buffer and the fastest slew rate. MEDIUM produces a medium drive (14 mA at 5V) buffer, while SLOW yields a standard (6 mA at 5V) buffer.
TRI-STATE	The output of each I/O can be made tri-state (0, 1 or Z), open source (1 or Z) or open drain (0 or Z) by programming an I/O's Source Selection mux. Of course, the output can be normal (0 or 1), as well.
SOURCE SELECTION MUX	The Source Selection mux selects the source for the output signal of an I/O.



Absolute Maximum Ratings – 3.3V Commercial/Industrial*

Operating Temperature55°C to +125°C
Storage Temperature65 °C to +150°C
Voltage on Any Pin with Respect to Ground0.5V to $\rm V_{\rm CC}$ +7V
Supply Voltage (V $_{\rm CC}$)0.5V to +7.0V
Maximum Soldering Temp. (10 sec. @ 1/16 in.)250°C
ESD (R _{ZAP} = 1.5K, C _{ZAP} = 100 pF)

*NOTICE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those listed under operating conditions is not implied. Exposure to Absolute Maximum Rating conditions for extended periods of time may affect device reliability.

DC and AC Operating Range – 3.3V Operation

		Commercial	Industrial	
Operating Temperature (Case)		0°C - 70°C	-40°C - 85°C	
V _{CC} Power Supply		3.3V ± 0.3V	3.3V ± 0.3V	
	High (V _{IHC})	70% - 100% V _{CC}	70% - 100% V _{CC}	
	Low (V _{ILC})	0 - 30% V _{CC}	0 - 30% V _{CC}	

<u>AMEL</u>

Power-On Power Supply Requirements

Atmel FPGAs require a minimum rated power supply current capacity to insure proper initialization, and the power supply ramp-up time does affect the current required. A fast ramp-up time requires more current than a slow ramp-up time.

Table 3. Power-On Power Supply Requirements⁽¹⁾

Device	Description	Maximum Current ⁽²⁾⁽³⁾
AT40K05AL AT40K10AL	Maximum Current Supply	50 mA
AT40K20AL AT40K40AL	Maximum Current Supply	100 mA

Notes: 1. This specification applies to Commercial and Industrial grade products only.

2. Devices are guaranteed to initialize properly at 50% of the minimum current listed above. A larger capacity power supply may result in a larger initialization current.

3. Ramp-up time is measured from 0 V DC to 3.6 V DC. Peak current required lasts less than 2 ms, and occurs near the internal power on reset threshold voltage.

AC Timing Characteristics – 3.3V Operation

Delays are based on fixed loads and are described in the notes. Maximum times based on worst case: $V_{CC} = 3.00V$, temperature = 70°C Minimum times based on best case: $V_{CC} = 3.60V$, temperature = 0°C Maximum delays are the average of t_{PDLH} and t_{PDHL}.

Cell Function	Parameter	Path	-1	Units	Notes
Core					
2-input Gate	t _{PD} (Maximum)	x/y -> x/y	1.8	ns	1 unit load
3-input Gate	t _{PD} (Maximum)	x/y/z -> x/y	2.1	ns	1 unit load
3-input Gate	t _{PD} (Maximum)	x/y/w -> x/y	2.2	ns	1 unit load
4-input Gate	t _{PD} (Maximum)	x/y/w/z -> x/y	2.2	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	y -> y	1.4	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	x -> y	1.7	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	y -> x	1.8	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	X -> X	1.5	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	w -> y	2.2	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	W -> X	2.3	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	z -> y	2.3	ns	1 unit load
Fast Carry	t _{PD} (Maximum)	Z -> X	1.7	ns	1 unit load
DFF	t _{PD} (Maximum)	q -> x/y	1.8	ns	1 unit load
DFF	t _{PD} (Maximum)	R -> x/y	2.2	ns	1 unit load
DFF	t _{PD} (Maximum)	S -> x/y	2.2	ns	1 unit load
DFF	t _{PD} (Maximum)	q -> w	1.8	ns	
Incremental -> L	t _{PD} (Maximum)	x/y -> L	1.5	ns	1 unit load
Local Output Enable	t _{PZX} (Maximum)	oe -> L	1.4	ns	1 unit load
Local Output Enable	t _{PXZ} (Maximum)	oe -> L	1.8	ns	



FreeRAM Asynchronous Timing Characteristics

Single-port Write/Read







Dual-port Read





FreeRAM Synchronous Timing Characteristics

Single-port Write/Read



AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL		Left Si	ide (Top to B	ottom)	
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
GND	GND	GND	GND	12	1	1	2	1
I/O1, GCK1 (A16)	I/O1, GCK1 (A16)	I/O1, GCK1 (A16)	I/O1, GCK1 (A16)	13	2	2	4	2
I/O2 (A17)	I/O2 (A17)	I/O2 (A17)	I/O2 (A17)	14	3	3	5	3
I/O3	I/O3	I/O3	I/O3			4	6	4
I/O4	I/O4	I/O4	I/O4			5	7	5
I/O5 (A18)	I/O5 (A18)	I/O5 (A18)	I/O5 (A18)	15	4	6	8	6
I/O6 (A19)	I/O6 (A19)	I/O6 (A19)	I/O6 (A19)	16	5	7	9	7
			GND					
			I/07					
			I/O8					
			I/O9					
			I/O10					
		I/07	I/O11					
		I/O8	I/O12					
		VCC	VCC					
		GND	GND					
			I/O13					
			I/O14					
I/07	I/07	I/O9	I/O15				10	8
I/O8	I/O8	I/O10	I/O16				11	9
	I/O9	I/O11	I/O17				12	10
	I/O10	I/O12	I/O18				13	11
			GND					
			I/O19					
			I/O20					
	I/O11	I/O13	I/O21					12
	I/O12	I/O14	I/O22					13
		I/O15	I/O23					
		I/O16	I/O24					
GND	GND	GND	GND			8	14	14
Note: 1. On	-chip tri-state							





AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL		Left Si	de (Top to B	ottom)	
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O9, FCK1	I/O13, FCK1	I/O17, FCK1	I/O25, FCK1			9	15	15
I/O10	I/O14	I/O18	I/O26			10	16	16
I/O11 (A20)	I/O15 (A20)	I/O19 (A20)	I/O27 (A20)	17	6	11	17	17
I/O12 (A21)	I/O16 (A21)	I/O20 (A21)	I/O28 (A21)	18	7	12	18	18
	VCC	VCC	VCC					19
	I/O17	I/O21	I/O29					20
	I/O18	I/O22	I/O30					21
			GND					
			I/O31					
			I/O32					
			I/O33					
			I/O34					
		I/O23	I/O35					
		I/O24	I/O36					
		GND	GND					22
			VCC					
			I/O37					
			I/O38					
		I/O25	I/O39					
		I/O26	I/O40					
	I/O19	I/O27	I/O41				19	23
	I/O20	I/O28	I/O42				20	24
			GND					
I/O13	I/O21	I/O29	I/O43			13	21	25
I/O14	I/O22	I/O30	I/O44		8	14	22	26
			I/O45					
			I/O46					
I/O15 (A22)	I/O23 (A22)	I/O31 (A22)	I/O47 (A22)	19	9	15	23	27
I/O16 (A23)	I/O24 (A23)	I/O32 (A23)	I/O48 (A23)	20	10	16	24	28
GND	GND	GND	GND	21	11	17	25	29
VCC	VCC	VCC	VCC	22	12	18	26	30
Note: 1 On	-chip tri-state	1	1	1		1		



AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL		Left Si	ide (Top to B	ottom)	
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
	I/O38	I/O52	I/O76					47
			I/077					
			I/O78					
			GND					
			I/O79					
			I/O80					
	I/O39	I/O53	I/O81				38	48
	I/O40	I/O54	I/O82				39	49
I/O25	I/O41	I/O55	I/O83				40	50
I/O26	I/O42	I/O56	I/O84				41	51
		GND	GND					
		VCC	VCC					
		I/O57	I/O85					
		I/O58	I/O86					
			I/O87					
			I/O88					
I/O27	I/O43	I/O59	I/O89	27	18	28	42	52
I/O28	I/O44	I/O60	I/O90		19	29	43	53
			GND					
			I/O91					
			I/O92					
I/O29	I/O45	I/O61	I/O93			30	44	54
I/O30	I/O46	I/O62	I/O94			31	45	55
I/O31 (OTS) ⁽¹⁾	I/O47 (OTS) ⁽¹⁾	I/O63 (OTS) ⁽¹⁾	I/O95 (OTS) ⁽¹⁾	28	20	32	46	56
I/O32, GCK2	I/O48, GCK2	I/O64, GCK2	I/O96, GCK2	29	21	33	47	57
M1	M1	M1	M1	30	22	34	48	58
GND	GND	GND	GND	31	23	35	49	59
MO	MO	MO	MO	32	24	36	50	60
Note: 1. On	-chip tri-state							



AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Right Side (Bottom to Top)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O73, FCK3	I/O111, FCK3	I/O147, FCK3	I/O219, FCK3			82	120	138
I/074	I/O112	I/O148	I/O220			83	121	139
	VCC	VCC	VCC					140
l/O75 (D5)	I/O113 (D5)	I/O149 (D5)	I/O221 (D5)	59	57	84	122	141
I/O76 (CS0)	I/O114 (CS0)	I/O150 (CS0)	I/O222 (CS0)	60	58	85	123	142
			GND					
			I/O223					
			I/O224					
			I/O225					
			I/O226					
		I/O151	I/O227					
		I/O152	I/O228					
		GND	GND					143
			VCC					
			I/O229					
			I/O230					
		I/O153	I/O231					
		I/O154	I/O232					
	I/O115	I/O155	I/O233				124	144
	I/O116	I/O156	I/O234				125	145
			GND					
I/077	I/O117	I/O157	I/O235		59	86	126	146
I/O78	I/O118	I/O158	I/O236		60	87	127	147
			I/O237					
			I/O238					
I/O79(D4)	I/O119(D4)	I/O159(D4)	I/O239(D4)	61	61	88	128	148
I/O80	I/O120	I/O160	I/O240	62	62	89	129	149
VCC	VCC	VCC	VCC	63	63	90	130	150
GND	GND	GND	GND	64	64	91	131	151
I/O81 (D3)	I/O121 (D3)	I/O161 (D3)	I/O241 (D3)	65	65	92	132	152
I/O82 (CHECK)	I/O122 (CHECK)	I/O162 (CHECK)	I/O242 (CHECK)	66	66	93	133	153

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL		Top Si	Top Side (Right to Left)		
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
GND	GND	GND	GND	76	77	110	160	182
I/O97 (A0)	I/O145 (A0)	I/O193 (A0)	I/O289 (A0)	77	78	111	161	183
I/O98, GCK7 (A1)	I/O146, GCK7 (A1)	I/O194, GCK7 (A1)	I/O290, GCK7 (A1)	78	79	112	162	184
I/O99	I/O147	I/O195	I/O291			113	163	185
I/O100	I/O148	I/O196	I/O292			114	164	186
			I/O293					
			I/O294					
			GND					
			I/O295					
			I/O296					
I/O101 (CS1,A2)	I/O149 (CS1,A2)	I/O197 (CS1,A2)	I/O297 (CS1,A2)	79	80	115	165	187
I/O102 (A3)	I/O150 (A3)	I/O198 (A3)	I/O298 (A3)	80	81	116	166	188
		I/O199	I/O299					
		I/O200	I/O300					
		VCC	VCC					
		GND	GND					
	I/O151 ⁽¹⁾	I/O201 ⁽¹⁾	I/O301 ⁽¹⁾	75 ⁽¹⁾ NC	76 ⁽¹⁾ NC	109 ⁽¹⁾ NC	159 ⁽¹⁾ NC	189 ⁽¹⁾ NC
	I/O152	I/O202	I/O302					190
I/O103	I/O153	I/O203	I/O303			117	167	191
I/O104 ⁽¹⁾	I/O154	I/O204	I/O304				168	192
			I/O305					
			I/O306					
			GND					
			I/O307					
			I/O308					
	I/O155	I/O205	I/O309				169	193
	I/O156	I/O206	I/O310				170	194
		I/O207	I/O311					195
		I/O208	I/O312					
GND	GND	GND	GND			118	171	196
Note: 1. Sha	ared with TSTCLK	K. No Connect.						

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AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Top Side (Right to Left)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O113 (A8)	I/O169 (A8)	I/O225 (A8)	I/O337 (A8)	3	90	129	184	213
I/O114 (A9)	I/O170 (A9)	I/O226 (A9)	I/O338 (A9)	4	91	130	185	214
			I/O339					
			I/O340					
			I/O341					
			I/O342					
			GND					
I/O115	I/O171	I/O227	I/O343		92	131	186	215
I/O116	I/O172	I/O228	I/O344		93	132	187	216
	I/O173	I/O229	I/O345				188	217
	I/O174	I/O230	I/O346				189	218
I/O117 (A10)	I/O175 (A10)	I/O231 (A10)	I/O347 (A10)	5	94	133	190	220
I/O118 (A11)	I/O176 (A11)	I/O232 (A11)	I/O348 (A11)	6	95	134	191	221
			VCC					
		GND	GND					
		I/O233	I/O349					
		I/O234	I/O350					
			I/O351					
			I/O352					
			I/O353					
			I/O354					
			GND					
		I/O235	I/O355					
		I/O236	I/O356					
	VCC	VCC	VCC					222
	I/O177	I/O237	I/O357					223
	I/O178	I/O238	I/O358					224
I/O119	I/O179	I/O239	I/O359			135	192	225
I/O120	I/O180	I/O240	I/O360			136	193	226
GND	GND	GND	GND			137	194	227
		I/O241	I/O361					
Note: 1. Sha	ared with TSTCL	K. No Connect.						





AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Top Side (Right to Left)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
		I/O242	I/O362					
	I/O181	I/O243	I/O363				195	228
	I/O182	I/O244	I/O364				196	229
			I/O365					
			I/O366					
			GND					
			I/O367					
			I/O368					
I/O121	I/O183	I/O245	I/O369				197	230
I/O122	I/O184	I/O246	I/O370				198	231
I/O123 (A12)	I/O185 (A12)	I/O247 (A12)	I/O371 (A12)	7	96	138	199	232
I/O124 (A13)	I/O186 (A13)	I/O248 (A13)	I/O372 (A13)	8	97	139	200	233
		GND	GND					
		VCC	VCC					
		I/O249	I/O373					
		I/O250	I/O374					
			I/O375					
			I/O376					
			I/O377					
			I/O378					
			GND					
	I/O187	I/O251	I/O379					234
	I/O188	I/O252	I/O380					235
I/O125	I/O189	I/O253	I/O381			140	201	236
I/O126	I/O190	I/O254	I/O382			141	202	237
l/O127 (A14)	I/O191 (A14)	I/O255 (A14)	I/O383 (A14)	9	98	142	203	238
I/O128, GCK8 (A15)	I/O192, GCK8 (A15)	I/O256, GCK8 (A15)	I/O384, GCK8 (A15)	10	99	143	204	239
VCC Note: 1. Sha	VCC ared with TSTCLK	VCC No Connect.	VCC	11	100	144	205	240

Part/Package Availability and User I/O Counts (including Dual-function Pins)

Package ⁽¹⁾	AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL
84 PLCC	62	62	_	62
100 TQFP	78	78	78	_
144 LQFP	114	114	114	114
208 PQFP	128	161	161	161
240 PQFP	_	_	_	193

Note: 1. Devices in same package are pin-to-pin compatible.

Package Type			
84J	84-lead, Plastic J-leaded Chip Carrier (PLCC)		
100T1	100-lead, Thin (1.0 mm) Plastic Quad Flat Package (TQFP)		
144L1	144-lead, Low-profile (1.4 mm) Plastic Quad Flat Package (LQFP)		
208Q1	208-lead, Plastic Quad Flat Package (PQFP)		
240Q1	240-lead, Plastic Quad Flat Package (PQFP)		

